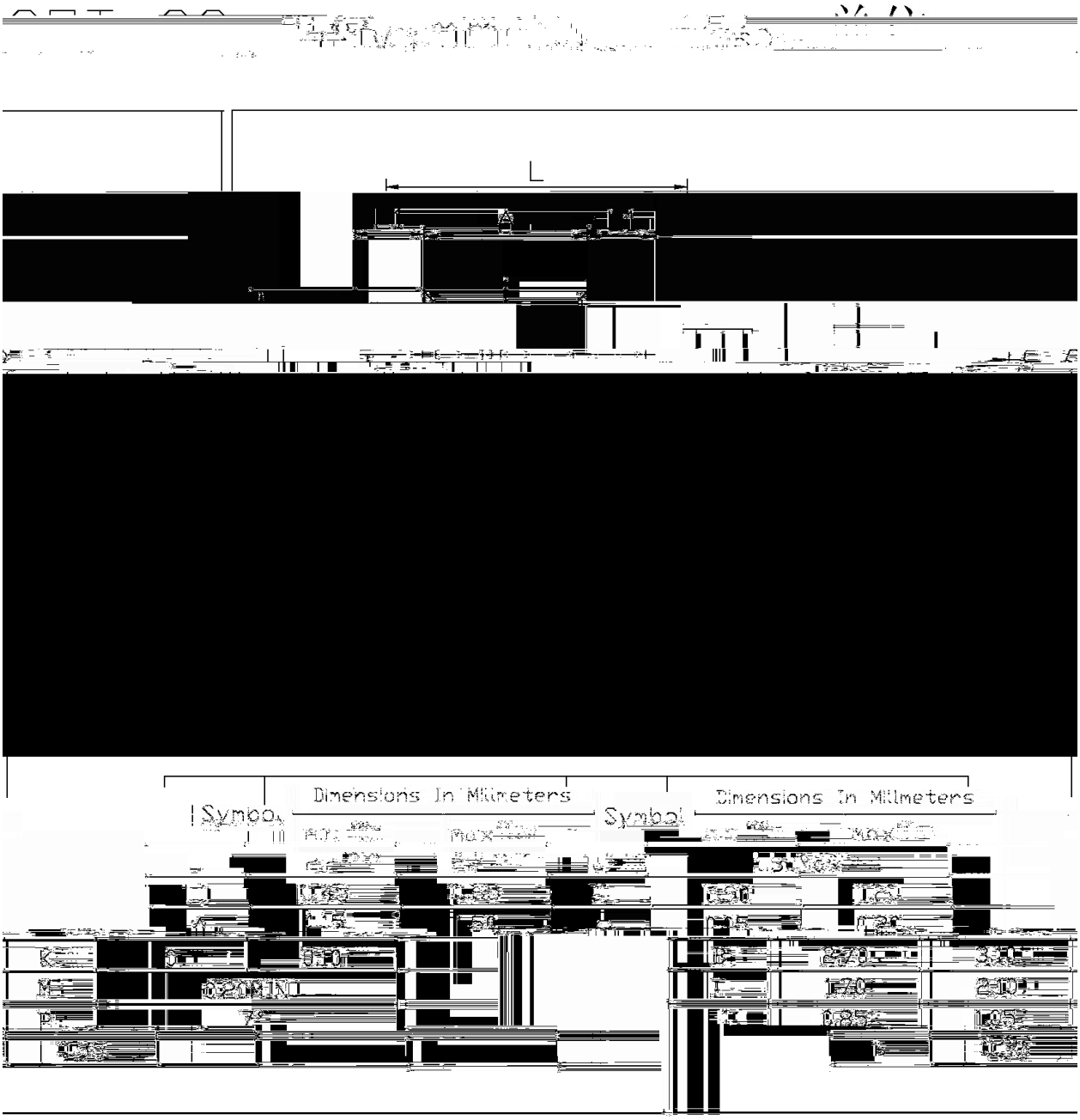
| | ! " # | $ ! % & ' | ! ( ) % * + | , - | . / |
|---|---|---|---|---|---|
| | | | | | |
| | | | 0 1 2 3 4 5 6 7 8 | 9 : ; | < = > |
| | | | ?@4 4 A 0 1 ) B C 3 4 D E 7 8 F G H I J K L M N O P Q R S T U D E B C % V W Q R X Y Z [ \ A ] ^ _ ` A a b c d \ e f \ g ] ^ _ ` A a b c d \ h | i j | < = > |
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SOT-23 NPN Silicon NPN transistor in a SOT-23

| Parameter | Symbol |
| --- | --- |

## / Package Dimensions



## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

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Note:

| | | | | | |
|---|---|---|---|---|---|
| 1 | 150 | 200 | 60 | 120sec; | 1.Preheating:150~200℃, Time:60~120sec. |
| 2 | 255±5 | | | 5±0.5sec; | 2.Peak Temp.:255±5℃, Duration:5±0.5sec. |
| 3 | | 2 | 10℃/sec. | | 3. Cooling Speed: 2~10℃/sec. |

## / Resistance to Soldering Heat Test Conditions

| | | | |
|---|---|---|---|
| 260±5℃ | 10±1 sec. | Temp.:260±5 | Time:10±1 sec |

## / Packaging SPEC.

/ REEL

| Package Type 封装形式 | Units 包装数量 | | | | | Dimension 包装尺寸 (unit: $mm^3$) | | |
|---|---|---|---|---|---|---|---|---|
| | Units/Reel / | Reels/Inner Box / | Units/Inner Box / | Inner Boxes/Outer Box | Units/Outer Box | | | |
| SOT-23 | 3,000 | 10 | 30,000 | 6 | 180,000 | 7″ ×8 | 180×120×180 | 390×385×205 |